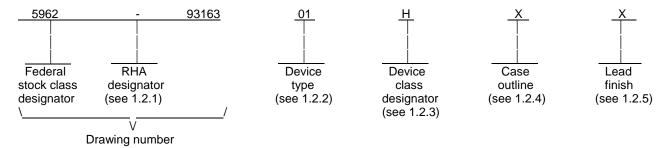
								R	EVISI	ONS										
LTR	DESCRIPTION					DATE (YR-MO-DA			DA)	APPROVED			)							
А	Chai	naes ii	n acco	rdance	e with	NOR :	5962-1	R247-9	94					94-0	7-25		K. A. Cottongim			
							0002 1	(217 )	<u> </u>								K. A. Cottongim  K. A. Cottongim			
В				s T, U											)2-23					
С	limits	Added device type 02. Updated table I for the addition of limits for the device type 02. Updated paragraph 4.3.5 to RadHard requirements. Redrew entire documentsld.						.5 to a	adHar dd the	d		02-0	)6-21		Ray	Raymond Monnin				
REV SHEET																				
	C	С	С																	
SHEET	C 15	C 16	C 17																	
SHEET REV SHEET REV STATU	15 S			REV			C	C	C	C	С	C	C	C	C	C	C	C	C	C
SHEET REV SHEET REV STATU OF SHEETS	15 S			RE\ SHE			C 1	C 2	C 3	C 4	C 5	C 6	C 7	C 8	C 9	C 10	C 11	C 12	C 13	C 14
SHEET REV SHEET REV STATU OF SHEETS PMIC N/A	15 S	16		SHE	EET	ED BY incan	1				5	6	7 SE SI	8 UPPL	9 Y <b>CE</b>	10	11 COL	12 .UMB	13	ļ
SHEET REV SHEET REV STATU OF SHEETS PMIC N/A STA	15 S	16 D		SHE PRE Ste	EET PARE ve Du	ıncan	1				5	6 EFEN	7 SE SI POS	8 UPPL ST OF	9 Y CE FICE , OHIO	10	11 3990 216-56	12 .UMB	13	ļ
SHEET REV SHEET REV STATU OF SHEETS PMIC N/A STA MICRO DR. THIS D AVA FOR U	NDAR OCIRC AWING	16 SUIT G IG IS E ALL		SHE PRE Ste CHE Mic	EPARE EVE DU CKEE CHAEL (	incan D BY	1 es	2		4 MIC	5 DI	6 EFEN CC	SE SI POS DLUM http	8 UPPL ST OF IBUS 0://ww	9 Y CE FICE , OHIO	NTER BOX O 432	11 3990 216-50 a.mil	12 .UMB 000	us /OLT	14
SHEET REV SHEET REV STATU OF SHEETS PMIC N/A STA MICRO DR. THIS D AVA FOR U	NDAR OCIRC AWING RAWING SE BY RTMEN NCIES	D CUIT G IG IS E ALL ITS OF TH	17	PRE Ste CHE Mic	EPARE eve Du CKEE chael (	D BY C. Jone ED BY A. Cotte	es ongim	2	3	4 MIC	5 DI	6 EFEN CC	SE SI POS DLUM http	8 UPPL ST OF IBUS 0://ww	9 Y CE FICE , OHIO	NTER BOX O 432 cc.dl	11 3990 216-50 a.mil	12 .UMB 000	us /OLT	14
SHEET REV SHEET REV STATU OF SHEETS PMIC N/A  STA MICRO DR.  THIS D AVA FOR U DEPA AND AGEN DEPARTMEN	NDAR OCIRC AWING RAWING SE BY RTMEN NCIES	DEFE	17	SHE PRE Ste CHE Mic APF Ker	ECKEE CHARE CRECKEE CHARE CRECKEE CHARE CRECKEE CHARE CRECKEE	ED BY A. Cotto	ongim	2	3	MIC SIN	5 DI	CIRCE CHA	SE SI POS DLUM http	8 UPPL ST OF IBUS, D://ww	9 Y CE FICE , OHIO	NTER BOX O 432 cc.dl:	11 3990 216-56 a.mil	12 .UMB .000 R, 5 \	us /OLT	-,

# 1. SCOPE

- 1.1 <u>Scope</u>. This drawing documents five product assurance classes as defined in paragraph 1.2.3 and MIL-PRF-38534. A choice of case outlines and lead finishes which are available and are reflected in the Part or Identifying Number (PIN). When available, a choice of radiation hardness assurance levels are reflected in the PIN.
  - 1.2 PIN. The PIN shall be as shown in the following example:



- 1.2.1 <u>Radiation hardness assurance (RHA) designator</u>. RHA marked devices shall meet the MIL-PRF-38534 specified RHA levels and shall be marked with the appropriate RHA designator. A dash (-) indicates a non-RHA device.
  - 1.2.2 <u>Device type(s)</u>. The device type(s) identify the circuit function as follows:

Device type	Generic number	<u>Circuit function</u>		
01	MFL2805S	DC-DC converter, 50 W, +5 V output		
02	SMFL2805S	DC-DC converter, 50 W, +5 V output		

1.2.3 <u>Device class designator</u>. This device class designator shall be a single letter identifying the product assurance level. All levels are defined by the requirements of MIL-PRF-38534 and require QML Certification as well as qualification (Class H, K, and E) or QML Listing (Class G and D). The product assurance levels are as follows:

Device class	Device performance documentation
К	Highest reliability class available. This level is intended for use in space applications.
Н	Standard military quality class level. This level is intended for use in applications where non-space high reliability devices are required.
G	Reduced testing version of the standard military quality class. This level uses the Class H screening and In-Process Inspections with a possible limited temperature range, manufacturer specified incoming flow, and the manufacturer guarantees (but may not test) periodic and conformance inspections (Group A, B, C and D).
E	Designates devices which are based upon one of the other classes (K, H, or G) with exception(s) taken to the requirements of that class. These exception(s) must be specified in the device acquisition document; therefore the acquisition document should be reviewed to ensure that the exception(s) taken will not adversely affect system performance.
D	Manufacturer specified quality class. Quality level is defined by the manufacturers internal, QML certified flow. This product may have a limited temperature range.

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1.2.4 <u>Case outline(s)</u>. The case outline(s) are as designated in MIL-STD-1835 and as follows:

Outline letter	Descriptive designator	<u>Terminals</u>	Package style
Т	See figure 1	12	Tabbed flange mount, lead formed up
U	See figure 1	12	Flange mount, lead formed down
Χ	See figure 1	12	Flange mount, short lead
Υ	See figure 1	12	Tabbed flange mount, short lead
Z	See figure 1	12	Tabbed flange mount, lead formed down

1.2.5 Lead finish. The lead finish shall be as specified in MIL-PRF-38534.

## 1.3 Absolute maximum ratings. 1/

Input voltage range 2/	-0.5 V dc to +50 V dc
Power dissipation (P <sub>D</sub> ):	
Device types 01and 02 (non-RHA)	18 W
Device type 02 (RHA level R)	20 W
Lead soldering temperature (10 seconds)	+300°C
Storage temperature range	-65°C to +150°C
1.4 Recommended operating conditions.	
Input voltage range (V <sub>IN</sub> )	+16 V dc to +40 V dc
Output power	≤ 50 W
Case operating temperature range (T <sub>C</sub> )	-55°C to +125°C

### 2. APPLICABLE DOCUMENTS

2.1 Government specification, standards, and handbooks. The following specification, standards, and handbooks form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those listed in the issue of the Department of Defense Index of Specifications and Standards (DoDISS) and supplement thereto, cited in the solicitation.

## **SPECIFICATION**

# DEPARTMENT OF DEFENSE

MIL-PRF-38534 - Hybrid Microcircuits, General Specification for.

### **STANDARDS**

## DEPARTMENT OF DEFENSE

MIL-STD-883 - Test Method Standard Microcircuits.

MIL-STD-1835 - Interface Standard for Electronic Component Case Outlines.

### **HANDBOOKS**

An undervoltage lockout circuit shuts the unit off when the input voltage drops to approximately 12 volts. Operation of the unit between 12 volts and 16 volts is nondestructive at reduced output power, but performance is not guaranteed.

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Stresses above the absolute maximum ratings may cause permanent damage to the device. Extended operation at the maximum levels may degrade performance and affect reliability.

### DEPARTMENT OF DEFENSE

MIL-HDBK-103 - List of Standard Microcircuit Drawings.

MIL-HDBK-780 - Standard Microcircuit Drawings.

(Unless otherwise indicated, copies of the specification, standards, and handbooks are available from the Standardization Document Order Desk, 700 Robbins Avenue, Building 4D, Philadelphia, PA 19111-5094.)

2.2 <u>Order of precedence</u>. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

## 3. REQUIREMENTS

- 3.1 <u>Item requirements</u>. The individual item performance requirements for device classes D, E, G, H, and K shall be in accordance with MIL-PRF-38534. Compliance with MIL-PRF-38534 may include the performance of all tests herein or as designated in the device manufacturer's Quality Management (QM) plan or as designated for the applicable device class. Therefore, the tests and inspections herein may not be performed for the applicable device class (see MIL-PRF-38534). Furthermore, the manufacturer may take exceptions or use alternate methods to the tests and inspections herein and not perform them. However, the performance requirements as defined in MIL-PRF-38534 shall be met for the applicable device class.
- 3.2 <u>Design, construction, and physical dimensions</u>. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38534 and herein.
  - 3.2.1 Case outline(s). The case outline(s) shall be in accordance with 1.2.4 herein and figure 1.
  - 3.2.2 <u>Terminal connections</u>. The terminal connections shall be as specified on figure 2.
- 3.3 <u>Electrical performance characteristics</u>. Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and shall apply over the full specified operating temperature range.
- 3.4 <u>Electrical test requirements</u>. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are defined in table I.
- 3.5 <u>Marking of device(s)</u>. Marking of device(s) shall be in accordance with MIL-PRF-38534. The device shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's vendor similar PIN may also be marked in MIL-HDBK-103 and QML-38534.
- 3.6 <u>Data</u>. In addition to the general performance requirements of MIL-PRF-38534, the manufacturer of the device described herein shall maintain the electrical test data (variables format) from the initial quality conformance inspection group A lot sample, for each device type listed herein. Also, the data should include a summary of all parameters manually tested, and for those which, if any, are guaranteed. This data shall be maintained under document revision level control by the manufacturer and be made available to the preparing activity (DSCC-VA) upon request.
- 3.7 <u>Certificate of compliance</u>. A certificate of compliance shall be required from a manufacturer in order to supply to this drawing. The certificate of compliance (original copy) submitted to DSCC-VA shall affirm that the manufacturer's product meets the performance requirements of MIL-PRF-38534 and herein.
- 3.8 <u>Certificate of conformance</u>. A certificate of conformance as required in MIL-PRF-38534 shall be provided with each lot of microcircuits delivered to this drawing.

### 4. QUALITY ASSURANCE PROVISIONS

4.1 <u>Sampling and inspection</u>. Sampling and inspection procedures shall be in accordance with MIL-PRF-38534 or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein.

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		TABLE I. Electrical perfo	ormano	ce characterist	ics.			
Test	Symbol	Symbol Conditions $\frac{1}{2}$ $-55^{\circ}C \le T_C \le +125^{\circ}C$ $V_{\text{IN}} = 28 \text{ V dc } \pm 0.5 \text{ V}$ no external sync unless otherwise specified		Group A subgroups	Device types	Limits		Unit
				Subgroups	турез	Min	Max	
Output voltage	V <sub>оит</sub>	I <sub>оит</sub> = 10 A dc		1	01,02	4.95	5.05	V
				2,3		4.875	5.125	
			R	1,2,3	02	4.70	5.30	
Output current	l <sub>out</sub>	V <sub>IN</sub> = 16 V dc to 40V dc		1,2,3	01,02	0.0	10	A
			R	1,2,3	02	0.0	10	
V <sub>ouт</sub> ripple voltage	$V_{RIP}$	I <sub>OUT</sub> = 10 A,		1	01,02		35	mVp-p
		B.W. = 10 kHz to 2 MHz	Z	2,3			50	
			R	1,2,3	02		75	
V <sub>ouт</sub> line regulation	VRLINE	lout = 10 A, V <sub>IN</sub> =16V dc to 40V dc		1,2,3	01,02		20	mV
			R	1,2,3	02		30	
V <sub>ouт</sub> load regulation	VR <sub>LOAD</sub>	I <sub>оит</sub> = 0 to 5 A		1,2,3	01,02		20	mV
			R	1,2,3	02		30	
Input current	I <sub>IN</sub>	I <sub>OUT</sub> = 0 A, Inhibit (pin 4 pin 12) = open	and	1,2,3	01,02		120	mA
			R	1,2,3	02		150	
		I <sub>OUT</sub> = 0 A, Inhibit 1(pin- tied to input return (pin-	1) 2)	1,2,3	01,02		14	
			R	1,2,3	02		17	]
		Iουτ = 0 A, Inhibit 2 (pin tied to output return (pir	12) 18)	1,2,3	01,02		70	
			R	1,2,3	02		90	
Short circuit current	I <sub>SC</sub>	V <sub>OUT</sub> < 1.0 V dc		1,2,3	01,02	8.8	12	А
			R	1,2,3	02	8.8	12	

See footnotes at end of table.

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Test	Symbol	Conditions <u>1/</u> -55°C < To < +125°	C	Group A subgroups	Device types	Limits		Unit
		V <sub>IN</sub> = 28 V dc ±0.5 v no external sync	$-55^{\circ}$ C ≤ $T_{C}$ ≤ $+125^{\circ}$ C $V_{IN}$ = 28 V dc $\pm 0.5$ V no external sync unless otherwise specified		туроз	Min	Max	
I <sub>IN</sub> ripple current	I <sub>RIP</sub>	louт = 10 A, B.W. = 10 kHz to 10 Mi	<b>-</b> 1-7	1	01,02		45	mAp-p
		B.W. = 10 KHZ to 10 WI	12	2,3			50	
			R	1,2,3	02		75	
Efficiency	Eff	Іоит = 10 А		1	01	77		%
					02	75		
				2,3	01	75		
					02	73		
			R	1,2,3	02	72		
Isolation	ISO	Input to output or any p case at 500 V dc, T <sub>C</sub> = +25°C	in to	1	01,02	100		ΜΩ
			R	1	02	100		
Capacitive load 2/3/	CL	No effect on dc performance, T <sub>C</sub> = +25°	°C	4	01,02		1000	μF
			R	4	02		1000	
Power dissipation load	P <sub>D</sub>	Short circuit		1	01,02		16	W
fault				2,3			18	
			R	1,2,3	02		20	
Switching frquency	Fs	lоит = 10 A		4	01,02	550	650	kHz
				5,6		525	675	
			R	4,5,6	02	500	700	
External sync range 4/	F <sub>SYNC</sub>	lout = 10 A, TTL level to	o pin	4,5,6	01,02	525	675	kHz
			R	4,5,6	02	525	675	

See footnotes at end of table.

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	TABLE	I. Electrical performance cha	acteristics - Cor	itinued.			
Test	Symbol	Conditions $\frac{1}{2}$ -55°C $\leq$ T <sub>C</sub> $\leq$ +125°C V <sub>IN</sub> = 28 V dc ±0.5 V	Group A subgroups	Device types	Lir Min	nits Max	Unit
		no external sync unless otherwise specified					
V <sub>оит</sub> step load transient <u>5</u> /	$V_{TLOAD}$	I <sub>OUT</sub> = 5 A to 10 A	4,5,6	01	-350	+350	mV pk
				02	-500	+500	_
		I <sub>OUT</sub> = 10 A to 5 A		01	-350	+350	_
				02	-500	+500	_
		I <sub>OUT</sub> = 5 A to 10 A	4,5,6	02	-1200	+1200	
		I <sub>OUT</sub> = 10 A to 5 A					
V <sub>OUT</sub> step load transient recovery 3/5/6/	TT <sub>LOAD</sub>	I <sub>OUT</sub> = 5 A to 10 A	4,5,6	01,02		3.0	ms
		R	4,5,6	02		4.0	
		I <sub>OUT</sub> = 10 A to 5 A	4,5,6	01,02		3.0	
		R	4,5,6	02		4.0	
V <sub>оит</sub> step line transient <u>3</u> / <u>7</u> /	V <sub>TLINE</sub>	louτ = 10 A, Input step 16 V dc to 40 V dc	4,5,6	01,02		300	mV pk
		R	4,5,6	02		400	
		louτ = 10 A, Input step 40 V dc to 16 V dc	4,5,6	01,02		300	
		R	4,5,6	02		400	
V <sub>ouτ</sub> step line transient recovery <u>3</u> / <u>6</u> / <u>7</u> /	TT <sub>LINE</sub>	I <sub>OUT</sub> = 10 A, Input step 16 V dc to 40 V dc	4,5,6	01,02		300	μs
		R	4,5,6	02		400	
		lout = 10 A, Input step 40 V dc to 16 V dc	4,5,6	01,02		300	
		R	4,5,6	02		400	
Start up overshoot 3/	Vtonos	lout = 10 A, V <sub>IN</sub> = 0 to 40 V	4,5,6	01,02		25	mV pk
		R	4,5,6	02		50	

See footnotes at end of table.

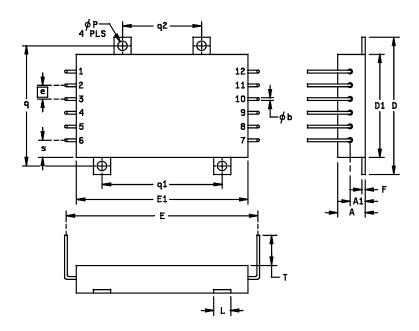
STANDARD MICROCIRCUIT DRAWING	SIZE <b>A</b>		5962-93163
DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216-5000		REVISION LEVEL C	SHEET <b>7</b>

TABLE I. <u>Electrical performance characteristics</u> - Continued.								
Test	Symbol	Conditions $1/$ $-55^{\circ}C \le T_C \le +125^{\circ}C$ $V_{IN} = 28 \text{ V dc } \pm 0.5 \text{ V}$ no external sync unless otherwise specified		Group A	Device	Lin	nits	Unit
				subgroups	types	Min	Max	
Start up delay <u>8</u> /	Ton₀	lout = 10 A, V <sub>IN</sub> = 0 to 28 V dc		4,5,6	01,02		6	ms
			R	4,5,6	02		12	
Load fault recovery 3/	Tr <sub>LF</sub>	louт = 10 A		4,5,6	01,02		4	ms
			R	4,5,6	02		8	

- 1/ Post irradiation testing shall be in accordance with 4.3.5 herein.
- 2/ Capacitive load may be any value from 0 to the maximum limit without compromising dc performance.
- 3/ Parameter shall be tested as part of design characterization and after design or process changes; therefore, the parameter shall be guaranteed to limits specified in table I.
- $\underline{4}$ / A TTL level waveform (V<sub>IH</sub> = 4.5 V minimum, V<sub>IL</sub> = 0.8 V maximum) with a 50 percent ±10 percent duty cycle applied to the sync input pin (pin 6) within the the sync range frequency shall cause the converter's switching frequency to become synchronous with the frequency applied to the sync input pin (pin 6).
- 5/ Load step transition time is between 2 and 10 microseconds.
- 6/ Recovery time is measured from the initiation of the transient until V<sub>OUT</sub> has returned to within ±1 percent of its final value.
- 7/ Input step transition time greater than 10 microseconds.
- 8/ Turn-on delay time measurement is either for a step application of power at the input or the removal of a ground signal from the inhibit 1 pin (pin 4) or inhibit 2 pin (pin 12) while power is applied to the input

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# Case outline T.



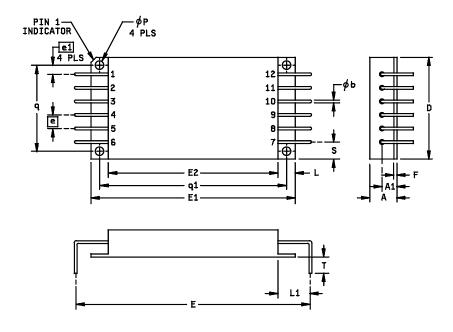
Symbol	Millin	neters	Inc	hes
	Min	Max	Min	Max
Α		10.16		.400
A1	5.33	5.84	.210	.230
φb	0.89	1.14	.035	.045
D	50.55	51.05	1.990	2.010
D1	37.85	38.35	1.490	1.510
е	5.08 BSC		.200	BSC
E	69.85	72.39	2.750	2.850
E1	63.25	63.75	2.490	2.510
F	1.14	1.40	.045	.055
L	6.10	6.60	.240	.260
φP	3.43	3.68	.135	.145
q/q1	44.20	44.70	1.740	1.760
q2	28.96	29.46	1.140	1.160
S	6.10	6.60	.240	.260
T	10.92	11.43	.430	.450

- NOTES:
  1. The U.S. government preferred system of measurement is the metric SI. This item was designed using inchpound units of measurement. In case of problems involving conflicts between the metric and inch-pound units, the inch-pound units shall rule.
  2. Device weight: 86 grams maximum.

FIGURE 1. Case outline(s).

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# Case outline U.



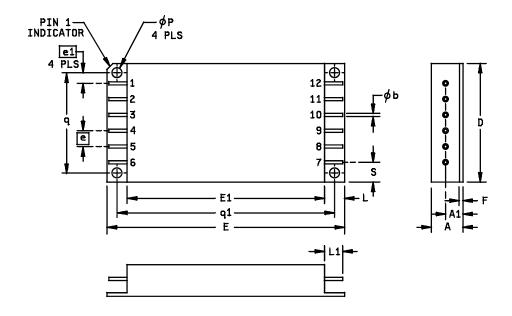
Symbol	Millin	neters	Inc	hes
	Min	Max	Min	Max
Α		10.16		.400
A1	5.46	5.72	.215	.225
φb	0.89	1.14	.035	.045
D	37.97	38.23	1.495	1.505
е	5.08	BSC	.200	BSC
e1	3.30	BSC	.130	BSC
E	87.38	87.88	3.440	3.460
E1	75.95	76.45	2.990	3.010
E2	63.37	63.63	2.495	2.505
F	1.14	1.40	.045	.055
L	6.10	6.60	.240	.260
L1	11.94	12.19	.470	.480
φP	3.12	3.38	.123	.133
q	31.88	32.13	1.255	1.265
q1	69.85	70.36	2.750	2.770
S	6.22	6.48	.245	.255
Т	5.84	6.86	.230	.270

- NOTES:
  1. The U.S. government preferred system of measurement is the metric SI. This item was designed using inch-pound units of measurement. In case of problems involving conflicts between the metric and inch-pound units, the inch-pound units shall rule.
  2. Device weight: 86 grams maximum.

FIGURE 1. Case outline(s) - Continued.

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DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216-5000		REVISION LEVEL C	SHEET 10

# Case outline X.



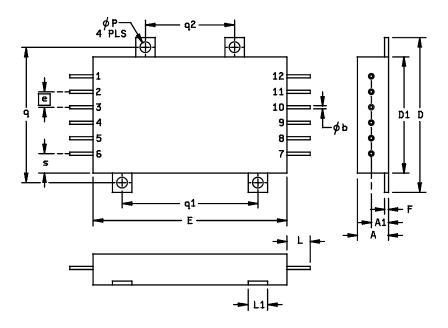
Symbol	Millin	neters	Inc	hes
	Min	Max	Min	Max
Α		10.16		.400
A1	5.46	5.72	.215	.225
φb	0.89	1.14	.035	.045
D	37.97	38.23	1.495	1.505
е	5.08	BSC	.200	BSC
e1	3.30	BSC	.130	BSC
E	75.95	76.45	2.990	3.010
E1	63.37	63.63	2.495	2.505
F	1.14	1.40	.045	.055
L	6.10	6.60	.240	.260
L1	5.58	6.10	.220	.240
φP	3.12	3.38	.123	.133
q	31.88	32.13	1.255	1.265
q1	69.85	70.36	2.750	2.770
S	6.22	6.48	.245	.255

- NOTES:
  1. The U.S. government preferred system of measurement is the metric SI. This item was designed using inchpound units of measurement. In case of problems involving conflicts between the metric and inch-pound units, the inch-pound units shall rule.
  2. Device weight: 86 grams maximum.

FIGURE 1. Case outline(s) - Continued.

STANDARD MICROCIRCUIT DRAWING	SIZE <b>A</b>		5962-93163
DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216-5000		REVISION LEVEL C	SHEET 11

# Case outline Y.



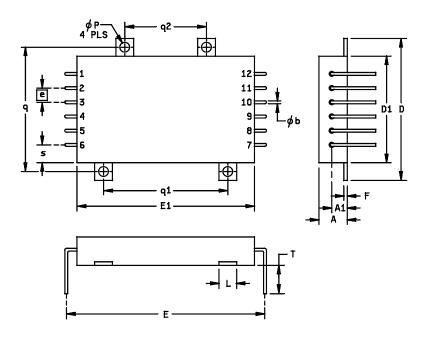
Symbol	Millin	neters	Inc	hes
	Min	Max	Min	Max
Α		10.16		.400
A1	5.33	5.84	.210	.230
φb	0.89	1.14	.035	.045
D	50.55	51.05	1.990	2.010
D1	37.85	38.35	1.490	1.510
е	5.08 BSC		.200 BSC	
E	63.25	63.75	2.490	2.510
F	1.14	1.40	.045	.055
L	6.99	8.26	.275	.325
L1	6.10	6.60	.240	.260
φP	3.43	3.68	.135	.145
q/q1	44.20	44.70	1.740	1.760
q2	28.96	29.46	1.140	1.160
S	6.10	6.60	.240	.260

- NOTES:
  1. The U.S. government preferred system of measurement is the metric SI. This item was designed using inchpound units of measurement. In case of problems involving conflicts between the metric and inch-pound units, the inch-pound units shall rule.
  2. Device weight: 86 grams maximum.

FIGURE 1. Case outline(s) - Continued.

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# Case outline Z.



Symbol	Millimeters		Inches	
	Min	Max	Min	Max
Α		10.16		.400
A1	5.33	5.84	.210	.230
φb	0.89	1.14	.035	.045
D	50.55	51.05	1.990	2.010
D1	37.85	38.35	1.490	1.510
е	5.08	BSC	.200 BSC	
Е	69.85	72.39	2.750	2.850
E1	63.25	63.75	2.490	2.510
F	1.14	1.40	.045	.055
L	6.10	6.60	.240	.260
φP	3.43	3.68	.135	.145
q/q1	44.20	44.70	1.740	1.760
q2	28.96	29.46	1.140	1.160
S	6.10	6.60	.240	.260
Т	8.64	9.65	.340	.380

- NOTES:
  1. The U.S. government preferred system of measurement is the metric SI. This item was designed using inchpound units of measurement. In case of problems involving conflicts between the metric and inch-pound units, the inch-pound units shall rule.
  2. Device weight: 86 grams maximum.

FIGURE 1. Case outline(s) - Continued.

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Device types	01 and 02
Case outlines	T, U, X, Y, and Z
Terminal number	Terminal symbol
1 2 3 4 5 6 7 8 9 10 11	Input Input common Tri Inhibit 1 Sync output Sync input Positive output Output common Remote sense return Positive remote sense Slave to master Master to slave/ Inhibit 2

### NOTES:

- 1. Multiple devices may be used in parallel to drive a common load. When using this mode of operation the load current is shared by two or three devices. In the current sharing mode, one device is designated as the master. The slave to master pin (pin 11) of the master device is not connected and the master to slave/inhibit 2 pin (pin 12) of the master is connected to the slave to master pin (pin 11) of the slave device(s). The device(s) designated as slave(s) have the master to slave/inhibit 2 pin (pin 11) connected to the remote sense return pin (pin 9).
- 2. A second slave device may be placed in parallel with a master and slave device, this requires the Tri pin (pin 3) of the master device to be connected to the remote sense pin (pin 9). When paralleled, 95 percent of the sum of the power of the devices is available at the load. This means that 143 watts at 5 volts is available for three devices in parallel. When using remote sense in parallel operation, only the master device should have its remote sense pins (pins 9 and 10) connected to the load, and the slave devices should have the remote sense pins (pins 9 and 10) connected to the output power pins (pins 7 and 8).
- 3. The device has a sync input pin (pin 6) and a sync output pin (pin 5) which allows multiple devices, whether they're in a single unit or master/slave configurations to be synchronized to a system clock or each other. Two or more devices may be synchronized to each other by connecting the sync output pin (pin 5) of one to the sync input pin (pin 6) of another.
- 4. The device has two inhibit options, one is ground referenced to the input common and the other is referenced to the output common. The output referred inhibit pin uses the master to slave/inhibit 2 pin (pin 12). This pin is normally used to parallel devices, and a TTL compatiable open collector low will inhibit the device when applied to this pin.

FIGURE 2. Terminal connections.

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TABLE II. Electrical test requirements.

MIL-PRF-38534 test requirements	Subgroups (in accordance with MIL-PRF-38534, group A test table)
Interim electrical parameters	
Final electrical parameters	1*, 2, 3, 4, 5, 6
Group A test requirements	1, 2, 3, 4, 5, 6
Group C end-point electrical parameters	1
End-point electrical parameters for radiation hardness assurance (RHA) devices	1, 2, 3, 4, 5, 6

<sup>\*</sup> PDA applies to subgroup 1.

- 4.2 Screening. Screening shall be in accordance with MIL-PRF-38534. The following additional criteria shall apply:
  - a. Burn-in test, method 1015 of MIL-STD-883.
    - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to either DSCC-VA or the acquiring activity upon request. Also, the test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015 of MIL-STD-883.
    - (2) T<sub>A</sub> as specified in accordance with table I of method 1015 of MIL-STD-883.
  - b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.
- 4.3 <u>Conformance and periodic inspections</u>. Conformance inspection (CI) and periodic inspection (PI) shall be in accordance with MIL-PRF-38534 and as specified herein.
  - 4.3.1 Group A inspection (CI). Group A inspection shall be in accordance with MIL-PRF-38534 and as follows:
    - a. Tests shall be as specified in table II herein.
    - b. Subgroups 7, 8, 9, 10, and 11 shall be omitted.
  - 4.3.2 Group B inspection (PI). Group B inspection shall be in accordance with MIL-PRF-38534.

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- 4.3.3 Group C inspection (PI). Group C inspection shall be in accordance with MIL-PRF-38534 and as follows:
  - a. End-point electrical parameters shall be as specified in table II herein.
  - b. Steady-state life test, method 1005 of MIL-STD-883.
    - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to either DSCC-VA or the acquiring activity upon request. Also, the test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005 of MIL-STD-883.
    - (2) T<sub>A</sub> as specified in accordance with table I of method 1005 of MIL-STD-883.
    - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.
- 4.3.4 Group D inspection (PI). Group D inspection shall be in accordance with MIL-PRF-38534.
- 4.3.5. <u>Radiation hardness assurance (RHA).</u> RHA qualification is required only for those devices with the RHA designator as specified herein.

	RHA level R	Units
Total ionizing dose tolerance level	100	kRad (Si)
Single event upset survival level (LET)	40	MeV

- a. Radiation dose rate is in accordance with condition C of method 1019 of MIL-STD-883. Unless otherwise specified, components are tested at a rate of 9 rad(Si)/s, in accordance with method 1019 of MIL-STD-750 or MIL-STD-883, as applicable.
- b. The manufacturer shall perform a worst-case and radiation susceptibility analysis on the device. This analysis shall show that the minimum performance requirements of each component has adequate design margin under worst-case operating conditions (extremes of line voltage, temperatures, load, frequency, radiation environment, etc.). This analysis guarantees the post-irradiation parameter limits specified in table I.
- c. RHA testing shall be performed at the component level for initial device qualification, and after design changes that may affect the RHA performance of the device. As an alternative to testing, components may be procured to manufacturer radiation guarantees that meet the minimum performance requirements. Component radiation performance guarantees shall be established in compliance with MIL-PRF-19500, Group D or MIL-PRF-38535, Group E, as applicable. For components with less than adequate performance margin, component lot radiation acceptance screening shall be performed.
- d. The manufacturer shall establish procedures controlling component radiation testing, and shall establish radiation test plans used to implement component lot qualification during procurement. Test plans and test reports shall be filed and controlled in accordance with the manufacturer's configuration management system.
- e. The device manufacturer shall designate a RHA program manager to oversee component lot qualification, and to monitor design changes for continued compliance to RHA requirements.

### 5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-PRF-38534.

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### 6. NOTES

- 6.1 <u>Intended use</u>. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.
- 6.2 <u>Replaceability</u>. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
- 6.3 <u>Configuration control of SMD's</u>. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished in accordance with MIL-PRF-38534.
- 6.4 <u>Record of users</u>. Military and industrial users shall inform Defense Supply Center Columbus when a system application requires configuration control and the applicable SMD. DSCC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronic devices (FSC 5962) should contact DSCC-VA, telephone (614) 692-0544.
- 6.5 <u>Comments</u>. Comments on this drawing should be directed to DSCC-VA, Post Office Box 3990, Columbus, Ohio 43216-5000, or telephone (614) 692-1081.
- 6.6 <u>Sources of supply</u>. Sources of supply are listed in MIL-HDBK-103 and QML-38534. The vendors listed in MIL-HDBK-103 and QML-38534 have submitted a certificate of compliance (see 3.7 herein) to DSCC-VA and have agreed to this drawing.

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## STANDARD MICROCIRCUIT DRAWING BULLETIN

DATE: 02-06-21

Approved sources of supply for SMD 5962-93163 are listed below for immediate acquisition information only and shall be added to MIL-HDBK-103 and QML-38534 during the next revisions. MIL-HDBK-103 and QML-38534 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DSCC-VA. This bulletin is superseded by the next dated revisions of MIL-HDBK-103 and QML-38534.

	1	
Standard	Vendor	Vendor
microcircuit drawing	CAGE	similar
	number	•
PIN <u>1</u> /	number	PIN <u>2</u> /
5962-9316301HTA	50821	MFL2805SW/883
5962-9316301HTC	50821	MFL2805SW/883
5962-9316302HTA	50821	SMFL2805SW/HO
5962-9316302HTC	50821	SMFL2805SW/HO
5962R9316302HTA	50821	SMFL2805SW/HR
5962R9316302HTC	50821	SMFL2805SW/HR
5962R9316302KTA	50821	SMFL2805SW/KR
5962R9316302KTC	50821	SMFL2805SW/KR
E060 00400041111A	E0004	MEL 20050V/202
5962-9316301HUA	50821	MFL2805SV/883
5962-9316301HUC	50821	MFL2805SV/883
5962-9316302HUA	50821	SMFL2805SV/HO
5962-9316302HUC	50821	SMFL2805SV/HO
5962R9316302HUA	50821	SMFL2805SV/HR
5962R9316302HUC	50821	SMFL2805SV/HR
5962R9316302KUA	50821	SMFL2805SV/KR
5962R9316302KUC	50821	SMFL2805SV/KR
5962-9316301HXA	50821	MFL2805S/883
5962-9316301HXC	50821	MFL2805S/883
5962-9316302HXA	50821	SMFL2805S/HO
5962-9316302HXC	50821	SMFL2805S/HO
5962R9316302HXA	50821	SMFL2805S/HR
5962R9316302HXC	50821	SMFL2805S/HR
5962R9316302KXA	50821	SMFL2805S/KR
5962R9316302KXC	50821	SMFL2805S/KR
33021133103021010	30021	OWI LZ0030/TCT
5962-9316301HYA	50821	MFL2805SY/883
5962-9316301HYC	50821	MFL2805SY/883
5962-9316302HYA	50821	SMFL2805SY/HO
5962-9316302HYC	50821	SMFL2805SY/HO
5962R9316302HYA	50821	SMFL2805SY/HR
5962R9316302HYC	50821	SMFL2805SY/HR
5962R9316302KYA	50821	SMFL2805SY/KR
5962R9316302KYC	50821	SMFL2805SY/KR
=000 004555 ···= /	<b>5055</b>	MEI 000-07/200
5962-9316301HZA	50821	MFL2805SZ/883
5962-9316301HZC	50821	MFL2805SZ/883
5962-9316302HZA	50821	SMFL2805SZ/HO
5962-9316302HZC	50821	SMFL2805SZ/HO
5962R9316302HZA	50821	SMFL2805SZ/HR
5962R9316302HZC	50821	SMFL2805SZ/HR
5962R9316302KZA	50821	SMFL2805SZ/KR
5962R9316302KZC	50821	SMFL2805SZ/KR

<sup>1/</sup> The lead finish shown for each PIN representing a hermetic package is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed contact the Vendor to determine its availability.

<sup>&</sup>lt;u>Z</u>/ <u>Caution</u>. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

# STANDARD MICROCIRCUIT DRAWING BULLETIN - CONTINUED.

DATE: 02-06-21

Vendor CAGE <u>number</u>

50821

Vendor name and address

Interpoint Corporation 10301 Willows Road Redmond, WA 98073-9705

The information contained herein is disseminated for convenience only and the Government assumes no liability whatsoever for any inaccuracies in the information bulletin.